

## Glued SAM data sheet SAM- $\lambda$ -A- $\tau$ -4.0-25.0g-c or 4.0-25.0g-e

GaAs chip area	standard:	4.0 mm x 4.0 mm
	optional:	other dimensions on request

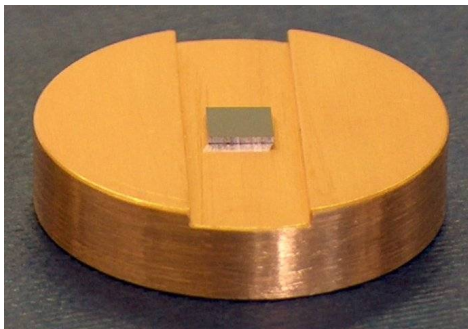
Chip thickness	standard:	450 $\mu$ m
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Front side protection	the SAM is protected with a dielectric front layer.
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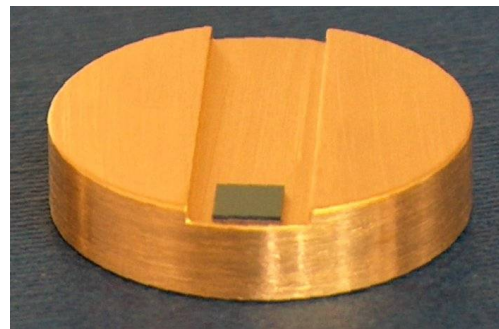
The SAM chip is glued on a gold plated Cu-cylinder with 25.0 mm  $\varnothing$  using a thermal conducting glue.

- The **standard** position of the SAM is at the center of the mount  $\rightarrow$  x = 4.0-25.0g-c.
- **Optional** the SAM can be mounted at the edge of the mount without extra charges  $\rightarrow$  x = 4.0-25.0g-e.

Center mounted SAM



Edge mounted SAM



### Mount

Cu-cylinder,  $\varnothing = 25.0$  mm  
l = 6.0 mm

